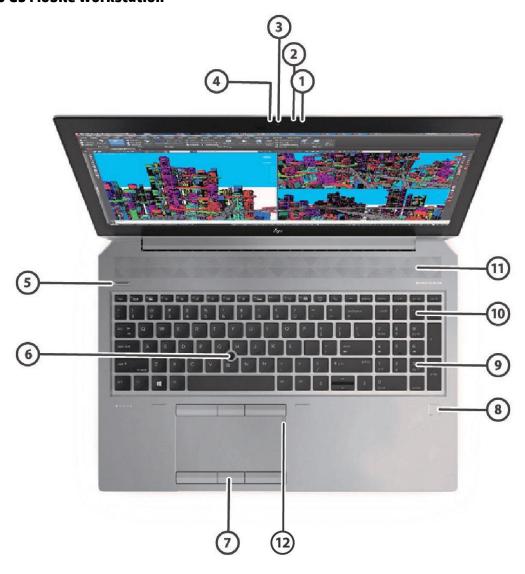
Overview

HP ZBook 15 G5 Mobile Workstation



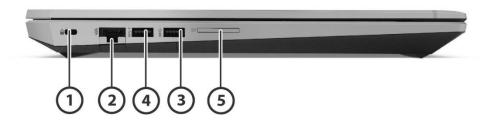
FRONT VIEW

- 1. Microphone
- 2. IR camera
- 3. Camera
- 4. HP Privacy Camera shutter
- 5. Power button
- 6. Pointstick

- 7. 3-button Touchpad
- 8. Fingerprint sensor
- 9. Numeric Keypad
- 10. Collaboration Keys
- 11. Speakers
- 12. Integrated Color Calibration Sensor



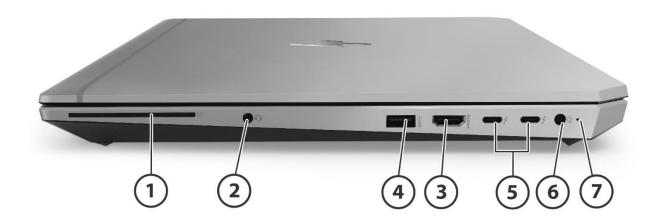
Overview



LEFT VIEW

- 1. Security cable slot
- 2. RJ-45/Ethernet
- 3. USB 3.0

- 4. USB 3.0 charging port
- 5. SD Card reader



RIGHT VIEW

- 1. Smart Card Reader
- 2. Stereo microphone in / headphone-out combo jack
- 3. HDMI 2.0

- 4. USB 3.0
- 5. (2) Thunderbolt™ 3 ports
- 6. Power connector
- 7. Power LED



Overview



BOTTOM VIEW

- 1. Fan Venting
- 2. Tool less access

3. Keyboard liquid drain

Overview

At A Glance

- Eye-catching industrial design, aluminum and magnesium-reinforced chassis with HP's turbo silver color provides optimal durability with minimal weight.
- Featuring HP Collaboration Keyboard with Clickpad to manage most commonly used conferencing functions with a single keystroke. HP Spill Resistant Keyboard with Durakeys to help protect keys from fading.
- ISV certified to provide fast and reliable performance with workstation applications, including manipulation of 3D textures
- HP Performance Advisor for optimal configuration, compatibility and performance
- Designed to pass MIL-STD-810G testing*.
- Optional Workstation-caliber graphics:
 - NVIDIA ® Quadro® discrete graphics featuring NVIDIA® Optimus techonology:
 - NVIDIA® Quadro® P1000 (4GB GDDR5)
 - NVIDIA® Ouadro® P2000 (4GB GDDR5)
 - AMD RadeonPro™ WX 4150 (4GB GDDR5) featuring AMD Enduro™ technology
- Intel® Integrated graphics: Intel® UHD Graphics 630 integrated on Core™ i7. Intel® UHD Graphics P630 integrated on Xeon® processors.
- Choice of 8th generation Intel® Core™ i5 quad-core and Intel® Core™ i7 hexa-core or Intel® Xeon® hexa-core processors
 with option Intel® vPro™ technology.
- Populate up to four SODIMM slots supporting up to 64 GB DDR4-2667MHz dual-channel memory. Up to 64GB ECC DDR4-2667MHz dual-channel memory available with Intel® Xeon® processors.
- Supports multi-display, including up to four (4) displays without a docking solution, with hybrid graphics enabled.
 Supports up to six (6) displays or (2) 4K displays with HP Thunderbolt™ Dock G2 (sold separately), with hybrid graphics enabled.
- Choice of 15.6-inch diagonal LED-backlit displays:
 - FHD IPS eDP anti-glare, 220 nits (1920x1080)
 - o FHD IPS eDP + PSR anti-glare, 400 nits with ambient light sensor (1920x1080)
 - HP Sure View FHD IPS eDP+PSR Touch-screen with Corning Gorilla Glass 4 650 nits (1920x1080)
 - UHD IPS eDP + PSR anti-glare, 400 nits with ambient light sensor (3840x2160)
 - UHD IPS eDP + PSR Touch-screen with Corning Gorilla Glass 4 400 nits with ambient light sensor (3840x2160)
 - HP DreamColor Technology, UHD IPS eDP + PSR anti-glare, 600 nits, 100% AdobeRGB with 10-bit color (3840x2160)
- Two (2) Thunderbolt[™] 3 ports (supporting DP 1.3, USB 3.1, PCIe Gen 3 devices) on the new USB-CTM connector, for high speed data/video/audio transfer support.
- Flexible wireless connectivity options:
 - o Intel® Dual Band Wireless-AC 9560 802.11 AC/a/b/g/n (2x2) WiFi and Bluetooth 5.0 combo adaptor (non-vPro™) or Intel® Dual Band Wireless-AC 9560 802.11 AC/a/b/g/n (2x2) WiFi and Bluetooth 5.0 combo adaptor (vPro™)
 - o Optional integrated wireless 4G (LTE) mobile broadband module support
- Optimize your audio experience for conference calls and remote collaboration with optional HD webcam, dual-array
 microphones, premium speakers, HP Noise Cancellation Software, HP Audio Boost, and audio. Custom-tuned by HP and
 Bang & Olufsen optimized for high fidelity audio with immersive surround sound with deep, rich bass and crystal-clear
 dialog without distortion at high volume, and new discrete amp.
- HP Long life battery solution: 4-cell (90 WHr) supporting HP Fast Charge capability
- Three (3) dedicated drive slots, two (2) M.2 slots, and one (1) 2.5"drive bays supporting up to 6TB of data.
- Enterprise grade security features including HP Client Security Manager, HP SureClick, HP WorkWise, HP SureView, and HP SureStart self healing BIOS. Low halogen HP BIOS technology, including HP Sure Start to identify and recover from unknown BIOS attacks. TPM 2.0, encrypted storage drives, fingerprint sensor, IR camera for Windows Hello, Integrated Smart Card Reader, BIOS Preboot power on, and Drive Encryption preboot option

*MIL STD 810G testing is pending and is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.



Overview

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Features

OPERATING SYSTEM

Preinstalled Windows 10 Pro 64¹

Windows 10 Pro for Workstations 641

Windows 10 Home 64¹

FreeDOS 2.0

Supported Windows 10 Enterprise 64¹

Red Hat® Enterprise Linux® (REHL)7

Ubuntu Linux 16.04

For additional Linux OS information, please reference our Linux Hardware Matrix:

http://h10032.www1.hp.com/ctg/Manual/c00060684.pdf

¹Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com

PROCESSOR

Intel® Core™ i7+ 8750H processor (Core i7 and 16GB Intel® Optane™ memory) with Intel® UHD Graphics 630 (2.2 GHz base frequency, up to 4.1 GHz with Intel® Turbo Boost Technology, 9 MB cache, 6 cores)

Intel® Core™ i7-8750H with Intel® UHD Graphics 630 (2.2 GHz base frequency, up to 4.1 GHz with Intel® Turbo Boost Technology, 9 MB cache, 6 cores)

Intel® Core™ i5+ 8300H (Core i5 and 16GB Intel® Optane™ memory) with Intel® UHD Graphics 630 (2.3 GHz base frequency, up to 4.0 GHz with Intel® Turbo Boost Technology, 8 MB cache, 4 cores)

Intel® Core™ i5-8300H with Intel® UHD Graphics 630 (2.3 GHz base frequency, up to 4.0 GHz with Intel® Turbo Boost Technology, 8 MB cache, 4 cores)

Intel® Core™ i5+ 8400H vPro™ processor (Core i5 and 16GB Intel® Optane™ memory) with Intel® UHD Graphics 630 (2.5 GHz base frequency, up to 4.2 GHz with Intel® Turbo Boost Technology, 8 MB cache, 4 cores)

Intel® Core™ i5-8400H vPro™ processor with Intel® UHD Graphics 630 (2.5 GHz base frequency, up to 4.2 GHz with Intel® Turbo Boost Technology, 8 MB cache, 4 cores)

Intel® Core™ i7+ 8850H vPro™ processor (Core i7 and 16GB Intel® Optane™ memory) with Intel® UHD Graphics 630 (2.6 GHz base frequency, up to 4.3 GHz with Intel® Turbo Boost Technology, 9 MB cache, 6 cores)

Intel® Core™ i7-8850H vPro™ processor with Intel® UHD Graphics 630 (2.6 GHz base frequency, up to 4.3 GHz with Intel® Turbo Boost Technology, 9 MB cache, 6 cores)

Intel® Xeon® E-2176M vPro™ processor with Intel® UHD Graphics P630 (2.7 GHz base frequency, up to 4.4 GHz with Intel® Turbo Boost Technology, 12 MB cache, 6 cores)

Intel® Xeon® E-2186M vPro™ processor with Intel® UHD Graphics P630 (2.9 GHz base frequency, up to 4.8 GHz with Intel® Turbo Boost Technology, 12 MB cache, 6 cores)

*Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

**Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system.

***Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.



Features

Note: In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD 7th generation and forward processors or provide any Windows®8 or Windows 7 drivers on http://www.support.hp.com

CHIPSET

Mobile Intel® CM246

INTEL® CORE™ I5 WITH VPRO/CORE I7 WITH VPRO/XEON® WITH VPRO TECHNOLOGY CAPABLE

Intel® Core™ i5 with vPro™, Core™ i7 with vPro™ and XEON® with vPro™ technology is a selectable feature that is available on units configured with select processors, a qualified Intel®® WLAN module and a preinstalled Windows® operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel® Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update regardless of their power state.

* Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

NOTE: Some functionality of Intel® Core™ i5 with vPro™/Core™ i7 with vPro™/Xeon® with vPro™ technology, such as Intel® Active Management technology and Intel® Virtualization technology, requires additional third- party software in order to run. Availability of future "virtual appliances" applications for Intel® Core™ i5 with vPro™/Core i7 with vPro™/XEON® with vPro™ technology is dependent on third- party software providers. Compatibility with future "virtual appliances" is yet to be determined.

GRAPHICS

Intel® Integrated

Intel® UHD graphics 630^{1,2}; Intel® UHD graphics P630^{1,2};

Discrete³

AMD RadeonPro™ WX 4150 with 4 GB dedicated GDDR5 video memory Microsoft DirectX 12 (Shader Model 5.0) and OpenGL 4.4 capable

NVIDIA® Quadro® P1000 with 4 GB dedicated GDDR5 video memory Microsoft DirectX 12 (Shader Model 5.0) and OpenGL 4.4 capable

NVIDIA® Quadro® P2000 with 4 GB dedicated GDDR5 video memory Microsoft DirectX 12 (Shader Model 5.0) and OpenGL 4.4 capable

NOTE 1: UHD content required to view UHD images.

NOTE 2: Intel® UHD graphics 630 is configurable as a standalone graphics option; Intel® UHD graphics P630 only used when NVIDIA® Optimus™ Technology is enabled.



Features

NOTE 3: NVIDIA® Quadro® mobile professional graphics support up to four independent displays when using a HP ZBook Dock with Thunderbolt™ 3 (sold separately) or DP 1.2 hubs with MST. AMD RadeonPro™ professional graphics support up to six independent displays when using an HP ZBook Dock with Thunderbolt™ 3 (sold separately) or DP 1.2 hubs with MST.

NOTE: Intel® HD Graphics 630 integrated on Core™ i7 and Core™ i5 processors. Intel® HD Graphics P630 integrated on Xeon® processors.

DisplayPort™ 1.3 protocol features supported on Thunderbolt™ 3 ports:

- Legacy displays (HDMI, DVI, VGA) may be attached to Thunderbolt™ port with the use of a certified dongle.
- DisplayPort™ monitors capable of supporting DisplayPort™ 1.3 may be directly attached to the Thunderbolt™ port to achieve HBR2 with the use a dongle.
- DisplayPort™ monitors capable of supporting DP 1.3 may be directly attached to the Thunderbolt™ port to achieve HBR2 with the use a dongle.
- Thunderbolt™ 3 enabled monitors may be directly attached to the Thunderbolt™ port to achieve HBR2 and MST.
- DisplayPort™ 1.3 MST feature ("daisy-chain" feature) is supported through Thunderbolt™ 3 port on Thunderbolt™ 3 enabled devices or DisplayPort™ 1.3 monitors (requires monitor with DisplayPort™ 1.3 MST capability) with the use of a dongle.
- Up to 2 streams (eight lanes) of DisplayPort™ 1.3 are supported over a single Thunderbolt™ 3 port. Up to (2) 4K displays 24/30-bit color depth at 60 Hz or (1) 5K display supported over a single Thunderbolt™ 3 port. (Requires Intel® certified Thunderbolt™ cable).
- DisplayPort™ 1.3 w/MST (Multi-stream Transport): Supports resolutions up to Full 4K, 24/30-bit color depth at 60 Hz, and WUXGA (1920 x1200) monitors, 24/30-bit color depth at 120 Hz.

*Thunderbolt™ 3 is superset port supporting DisplayPort™ 1.3, USB 3.1 Gen 2, and PCIe Gen 3 devices over the new USB-C™ connector. Install all the latest drivers for your Thunderbolt™ device before connecting the device to the Thunderbolt™ port. Thunderbolt™ cable and Thunderbolt™ device (sold separately) must be compatible with Windows. To determine whether your device is Thunderbolt™ Certified for Windows, see https://Thunderbolttechnology.net/products.

Multi-Display Support

Without HP Thunderbolt Dock G2:

HP ZBook 15 with hybrid graphics and without the use of the ZBook dock supports up to a maximum of four independent displays. These four displays are the internal panel plus three external displays connected to the three following ports: HDMI 2.0, Thunderbolt™ 3, Thunderbolt™ 3. HP ZBook 15 configuration with Intel® integrated graphics and without the use of the ZBook dock supports up to a maximum of three independent displays. Any three-display combination of the system panel: HDMI, Thunderbolt™ 3, Thunderbolt™ 3.

With HP Thunderbolt Dock G2:

The HP Thunderbolt Dock G2 has Thunderbolt™ 3 port, VGA, two DisplayPort™ 1.3, and a USB-C port. When used together with the HP ZBook 15 configuration with hybrid graphics, a maximum of 6 independent displays are supported. These six displays are internal panel, one external display connected to the system's HDMI port and four external displays connected to the ZBook dock's Thunderbolt™ 3, VGA, and two DisplayPort™ ports. When used together with the HP ZBook 15 configuration with Intel® integrated graphics, a maximum of 3 independent displays are supported. Any three display combination of the system panel, system ports and ZBook Dock ports.



Features

DISPLAY

Internal

- 15.6" diagonal FHD IPS eDP anti-glare LED-backlit, 220 nits (1920x1080)
- 15.6" diagonal FHD IPS eDP + PSR anti-glare LED-backlit, 400 nits with ambient light sensor (1920x1080)
- HP Sure View Display 15.6" diagonal FHD IPS eDP+PSR LED-backlit Touch-screen with Corning Gorilla Glass 4, 650 nits (1920x1080)
- 15.6" diagonal UHD IPS eDP + PSR anti-glare LED-backlit, 400 nits with ambient light sensor (3840x2160)
- 15.6" diagonal UHD IPS eDP + PSR LED-backlit Touch-screen with Corning Gorilla Glass 4 400 nits with ambient light sensor (3840x2160)
- HP DreamColor Display, 15.6" diagonal UHD IPS eDP + PSR anti-glare, RG phosphors LED-backlit, 600 nits, 100%
 AdobeRGB with 10-bit color (3840x2160) featuring Integrated Color Calibration Sensor on ClickPad to ensure color accuracy.

NOTE: Resolutions are dependent upon monitor capability, and resolution and color depth settings.

STORAGE AND DRIVES

(2) M.2

SATA SED Solid State Drives*

256 GB SATA Self Encrypting Drive (SED) Solid State Drive 512 GB SATA FIPS 140-2 SED Drive 16GB Intel® Optane Cache (Must be configured with HDD)

NVMe Solid State Drives

16 GB Intel® Optane™ memory**,***
256GB PCIe (NVMe) TLC Solid State Drive
512GB PCIe (NVMe) TLC Solid State Drive
1 TB PCIe (NVMe) TLC Solid State Drive
2 TB PCIe (NVMe) TLC Solid State Drive
256GB PCIe (NVMe) TLC Opal 2 Solide State Drive
512GB PCIe (NVMe) TLC Opal 2 Solide State Drive

(1) 2.5" Storage Bay Drives*

2 TB 5400 rpm SATA
2 TB SATA SSHD (Hybrid Drive) (8 GB cache)
1 TB SATA SSHD (Hybrid Drive) (8 GB cache)
1 TB 7200 rpm SATA
500 GB 7200 rpm SATA
500 GB SATA SSHD (Hybrid Drive) (8 GB cache)
500 GB 7200 rpm SATA SED (Self Encrypting Drive)
500 GB 5400 rpm SATA FIPS 140-2 SED Drive
256GB SATA SSD
1 TB SATA SSD

HP 3D DriveGuard (Windows only)

The hard drive is mounted directly to the notebook frame, reducing the transmission of shock to the hard drive. Uses three-axis digital motion detection with intelligent sensitivity to help protect the hard drive during normal use from shock and



Features

vibration. The digital accelerometer temporarily halts all data transfer and parks the hard drive when abrupt motion is detected.

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

**Must be configured with either a Hard Disk Drive or a Hybrid Drive. Cannot be configured with an additional M.2 SSD.

***Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system.



Features

DRIVE CONTROLLERS

2.5" Storage Bays and M.2 Storage Bay (SATA): SATA-3 or SATA-2 for HDD and SATA-3 for SSD

HP Z Turbo Drive: PCIe NVMe SSD RAID: 0, 1 supported*

NOTE: Raid 0, 1 supported only on SATA drives.

MEMORY

Standard

64 GB DDR4 ECC or Non-ECC SDRAM (With transfer rates up to 2667MT/s¹)
Four SODIMM slots supporting dual-channel memory; two SODIMMS slots are customer accessible or upgradeable 4 GB, 8GB and 16 GB SODIMMs (for Intel® Core™ Processors)
8GB and 16 GB ECC SODIMMs (for Intel® XEON® Processors)

Maximum

Upgradeable to 64 GB with optional 16 GB SODIMMs in all 4 slots

Dual-channel

Maximized dual-channel performance requires SODIMMs of the same size and speed in both memory channels.

NOTE 1: Only 2 DIMM configurations run at 2400 MHz. 4 DIMM configurations run at 2133 MHz.

NOTE: Maximum memory capacities assume Windows 64-bit operating systems. With Windows 32-bit operating systems, memory above 3 GB may not all be available due to system resource requirements.

NETWORKING/COMMUNICATIONS

Communications*

Intel® I219-LM Gigabit* Network Connection (vPro configurations)

Wireless

Support for a broad range of secure, integrated wireless LAN and wireless WAN options featuring support for the latest industry standards. Optional Broadband Wireless (WWAN) requires a Windows® operating system and is available in select countries as a standard, factory configurable feature only. Integrated Bluetooth® is also available (factory configurable only) and can be combined with any of the supported wireless LAN and wireless WAN options.

802.11 Wireless LAN options**

Intel® Dual Band Wireless-AC 9560 802.11ac (2x2) Wi-Fi® and Bluetooth® 5.0 Combo; Intel® Dual Band Wireless-AC 9560 802.11ac (2x2) Wi-Fi® and Bluetooth® 5.0 Combo, non-vPro™

Wireless WAN - Mobile Broadband options***

Intel® XMM™ 7360 LTE-Advanced
HP lt4132 LTE/HSPA+ 4G Mobile Broadband Module



Features

Near Field Communication¹

NFC Mirage WNC XRAV-1 (NXP NPC300 I2C 10mmx17mm)

*The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

**Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

***WWAN is an optional feature. WWAN use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, and in all regions.

¹Sold separately or as an optional feature.



Features

AUDIO/MULTIMEDIA

Audio¹

Audio custom-tuned by HP and Bang & Olufsen, dual stereo speakers
Dual array digital microphone
Optional World Facing microphone
Functions keys for volume up and down
Combo microphone/headphone jack
HD audio; featuring HP Noise Cancellation Software, HP Clear Sound Amp and Skype for Business Certification

Webcam*,**

Optional HP Privacy Camera (720p HD webcam)

Optional HP Privacy Camera (720p HD webcam) IR camera for face authentication with Windows Hello

- Privacy Camera features sliding camera shutter (non-touch only)
- HD format (widescreen)
- Supports videoconferencing and still image capture
- High quality fixed focus lens
- Video capture at various resolutions up to 1280x720 resolution (720p) and up to 30fps
- M-JPEG compression supports higher frame rates for video capture and videoconferencing
- Improved low light sensitivity
- Improved dynamic range

Note 1: Dual-microphone array when equipped with optional webcam and optional world facing microphone

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

Full-size, spill-resistant backlit HP Premium Collaboration Keyboard to manage most commonly used conferencing functions with a single keystroke with Durakeys to help protect keys from fading, featuring function key control and numeric keypad

Pointing Devices

Touchpad with On/Off button, two-way scroll, gestures, three pick buttons

Pointstick with three additional pointstick buttons

Image sensor touchpad for enhanced performance and improved precision on scroll and gesture

Buttons and Function Keys

Discrete buttons provide easy access to the following features:

F1 – Display Switching

F2 - HP Sure View (if configured)

F3 - Brightness Down

F4 - Brightness Up

F5 - Speaker mute

F6 - Volume down

F7 – Volume up

F8 – Microphone mute

F9 – Keyboard backlight



^{*} HD content required to view HD images.

^{**}Optional or add-on feature.

Features

F10 – NumLock

F11 - Wireless on/off

F12 – Calendar

F13 – Share screen

F14 – Call

F15 – End Call



Features

SOFTWARE AND SECURITY

Preinstalled Software with Windows® Operating System

BIOS

HP BIOSphere Gen41

HP Sure Start Gen4²

HP DriveLock | HP Automatic DriveLock

BIOS Update via Network

Master Boot Record Security

Power On Authentication

Secure Erase³

Absolute Persistence Module⁴

Pre-boot Authentication

HP LAN-WLAN Protection

Multi Media

Cyberlink Power MediaPlayer CMIT

Communication / Connectivity

HP Mobile Connect Pro5

Native Miracast Support⁶

HP MAC Address Manager (select models only)

HP Host Based Mac Address

HP Wireless Wakeup (select models only)

HP SureConnect

HP Value Add Software

HP 3D DriveGuard 6

HP ePrint Driver + JetAdvantage7

HP Hotkey Support

HP Recovery Manager

HP Jumpstart

HP Support Assistant¹²

HP Noise Cancellation Software

HP Performance Advisor

HP Remote Graphics Software

HP Velocity

Microsoft Products

Buv Office

Bing Search

Skype⁸

Manageability

HP Driver Packs 9

HP SoftPag Download Manager (SDM)

HP System Software Manager (SSM) 9

HP BIOS Config Utility (BCU) 9

HP Client Catalog 9

HP Manageability Integration Kit for Microsoft SCCM 10

HP Image Assistant

LANDESK Management 11

For more information on HP Client Management Solutions refer to: http://www.hp.com/go/clientmanagement.

Client Security Software

HP Client Security Suite Gen3¹³



Features

- HP Security Manager (including Credential Manager and Password Manager¹⁶)
- HP Fingerprint Sensor
- IR Camera with Windows Hello
- Device Access Manager
- Microsoft Defender 14
- HP WorkWise¹⁵

Standard

For Windows 10, Trusted Platform Module (TPM) 2.0 (Infineon SLB9670). Common Criteria EAL4+ Certified. For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

- 1. HP BIOSphere Gen4 requires Intel® or AMD 8th generation processors.
- 2. HP Sure Start Gen4 is available on HP Z Workstations products equipped with 8th generation Intel® or AMD processors.
- 3. HP Secure Disk Erase is for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88.
- 4. BIOS Absolute Persistence module is shipped turned off, and will be activated when customers purchase and activate a subscription. Service may be limited. Check with Absolute for availability outside the U.S. The optional subscription service of Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/computrace-agreement. If Data Delete is utilized, the Recovery Guarantee payment is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either create a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- 5. HP Mobile Connect Pro is only available on preconfigured devices with WWAN. For geographic availability refer to http://www.hp.com/go/mobileconnect
- 6. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast
- 7. Requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see http://www.hp.com/go/eprintcenter). Requires optional broadband module. Broadband use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Separately purchased data plans or usage fees may apply. Print times and connection speeds may vary.
- 8. Skype is not offered in China.
- 9. Not preinstalled, however available for download at http://www.hp.com/go/clientmanagement
- HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html
- 11. Subscription required.
- 12. Requires Windows and Internet Access
- 13. Requires Windows and Intel® 7th generation processors.
- 14. Opt in and internet connection required for updates
- 15. HP WorkWise smartphone app is available as a free download on the App Store and Google Play
- 16. HP Password manager requires Windows.

Workstation ISV Certifications

See the latest list of certifications at: http://www.hp.com/go/isv

HP Remote Graphics Software

The remote desktop solution for serious workstation users and their most demanding applications.

Download at: http://www.hp.com/go/RGS

HP Performance Advisor



Features

HP Performance Advisor enables optimal configuration of HP Mobile Workstations delivering stability and best performance. HP Performance Advisor will guide your system setup allowing a "custom" configuration that best matches the workstation to user requirements.

Download at: http://www.hp.com/go/performanceadvisor

Other Standard Security Features

BIOS Update via Network
Pre-boot Authentication
SATA 0,1 port disablement (viaBIOS)
RAID configurations
Serial, USB enable/disable (viaBIOS)
Power-on password (viaBIOS)

Support for chassis padlocks and cable lock devices

Measured Boot HP Sure Click¹

Integrated Smart Card Reader

Setup password (viaBIOS)

One-Step Logon Security lock slot Support for Intel® AT

TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)

HP Sure Run² HP Sure Recovery³

TPM

Model: Infineon SLB9670 Version: 7.63.3353.0 Revision: TPM 2.0 FIPS 140-2 Compliant: TBD Fingerprint Sensor (Optional)

Voltage: 3.0-3.6V

Operating temperature: -20° - 85°C

Imaging current: 31mA Wake on finger current: 40 uA Capture rate: 30ms/frame

ESD Resistance: IEC 6100-4-2 4B (+/-15KV)
Detection Matrix: 363 dpi, sensing area 8x8 mm

Smartcard Reader

Model number: Alcor AU9560

Optional Security Features

HP Fingerprint Sensor (optional)⁴
IR Camera with Windows Hello

Absolute Data Protect* with GPS Tracking - Subscription based security solution providing the ability to track, initiate physical recovery, conduct asset management, and perform remote data delete by utilizing GPS technology. GPS functionality requires HP Mobile Broadband Module.

- * The Absolute Data Protect agent is shipped turned off, and must be activated by customers when they purchase a subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S.
 - HP Sure Click is available on select platforms only as a web-download from the HP Support website, is preinstalled on select HP platforms and supports Microsoft® Internet Explorer and Chromium™. Check http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=4AA7-0922ENW for all compatible platforms as they become available.
 - 2. HP Sure Run is available on HP Elite products equipped with Intel® or AMD® 8th generation processors



Features

- 3. HP Sure Recover is available on HP Elite PCs with 8th generation Intel® or AMD processors and requires an open, wired network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data
- 4. Finger Sensor is optional



Features

HP CENTRAL MANAGEMENT

HP offers a variety of scalable hardware, software, and BIOS-based security features to help you defend your organization against viruses and other threats. These integrated security features safeguard what matters to you the most - your data, device and identity. Now, be confident your fleet of devices is protected in multiple layers of HP Client Security protection.

HP BIOS Protection keeps you up and running with enhanced protection against virus attacks and other threats. And if the BIOS is accidently compromised, the auto recovery feature automatically restores it to its fully functional state.

HP Sure Start detects and negates a BIOS attack with automatic recovery of the BIOS even when the installation is accidentally compromised (i.e. power outage). When HP Sure Start heals the BIOS an event log is generated that an IT administrator can retrieve so the business is aware of a BIOS attack. Golden copy of BIOS is stored in protected nonvolatile memory providing redundant, hardware-based protection against a new generation of attacks. This helps to future-proof your technology and business.

An optional fingerprint reader and integrated Smart Card Reader help keep your identity secure. The security cable slot helps keep your notebook physically secure.

You can even permanently destroy data on your hard drive in preparation for your system disposal or redeployment with Secure Erase.



Features

POWER

Power Supply

HP 150W Slim Smart AC adapter (153 x 66 x 22 mm)

Primary Battery

HP Long Life 4-cell Polymer Battery (90 WHr) *

NOTE: Battery is internal and not replaceable by the customer

Battery Life

Battery life up to 17 hours for UMA graphics only configuration **
Battery life up to 16.5 hours for Hybrid graphics configuration **

System Standby Time

Up to 1.8 weeks***

- * Available with 3-year limited warranty only
- ** Battery life will vary depending on the product model, configuration, loaded applications, features, use, wireless functionality and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See MobileMark14 battery benchmark https://bapco.com/products/mobilemark-2014/ for additional details.
- *** Standby life will vary depending on various factors including battery, Memory, CPU, EC and LAN chip. The maximum capacity of the battery will naturally decrease with time and usage.

Power Conservation

NVIDIA® Optimus or AMD Enduro™ technology Hibernation Standby ACPI compliance

ENVIRONMENTAL

US ENERGY STAR ® IT ECO declaration EPEAT® registered* Low Halogen**

- * EPEAT ® registered where applicable. EPEAT registration varies by country. See www.epeat.net for registration status by country. See HP's 3rd party option store for solar energy accessory www.hp.com/go/options.
- **External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

WEIGHTS & DIMENSIONS

Weight

Starting at 5.79 lb. (2.60kg.)



Features

Dimensions (w x d x h) 14.8 in x 10.4 in x 1.0 in 376 mm x 264 mm x 26 mm

NOTE: Height varies depending upon where on the notebook the measurement is made. Weight varies by configuration and components. Weight includes Quad Core CPU, FHD, Intel® HD graphics, 8GBx1 SODIMM, HP Z Turbo Drive, wLAN/BT, FPR, 9-cell battery, no wWAN.

PORTS/SLOTS

Ports

Left side:

- (1) RJ-45 (Ethernet)
- (1) USB 3.0 Charging Port
- (1) USB 3.0
- (1) Security lock slot

Right side:

- (1) HDMI 2.0
- (2) Thunderbolt™ 3* (Supporting DisplayPort™ 1.3, USB 3.1 Gen2, PCIe Gen 3 devices)
- (1) Stereo microphone in / headphone-out combo jack
- (1) Power Connector
- (1) USB 3.0

Thunderbolt™ 3

Thunderbolt[™]3 ports supports DisplayPort[™] 1.3, USB 3.1 Gen 2, and PCIe Gen 3 devices over the new USB-C port connector. The port is compatible with existing DisplayPort[™] displays, devices, and cables. Install all the latest drivers for your Thunderbolt[™] device before connecting the device to the Thunderbolt[™] port. Thunderbolt[™] cable and Thunderbolt[™] device (sold separately) must be compatible with Windows[®]. To determine whether your device is Thunderbolt[™] Certified for Windows, see https://thunderbolttechnology.net/products.

Digital Media Slots

- (1) SD UHS-II Flash Media slot (Supports next generation SD (Secure Digital), backward compatible to SDHC, SDXC,
- (1) Integrated Smart Card Reader (Compatible with ISO 7816 compliant Smart Cards PC/SC interface support)

SERVICE AND SUPPORT

Limited 3-year or 1-year limited warranty options available, depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Optional* HP Care Pack Services are extended service contracts which go beyond your standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at http://www.hp.com/go/cpc.

*Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product. Consult your local HP Customer Support Center for details.



Technical Specifications – System Unit

SYSTEM UNIT

Stand-Alone Power Nominal Operating 19.5 V

Requirements (AC Power) Voltage

Average Operating Power DreamColor 25W (Windows® 10 64-bit)

Without DreamColor 16.8 W (Windows® 10 64-bit)

Max Operating Power < 150 W

Temperature Operating 32° to 95° F (0° to 35° C)

Non-operating -4° to 140° F (-20° to 60° C)

Relative Humidity Operating 10% to 90%, non-condensing

Non-operating 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Shock Operating 40 G, 2 ms, half-sine

Non-operating 200 G, 2 ms, half-sine

Random Vibration Operating 0.75 grms

Non-operating 1.50 grms

Altitude (unpressurized) **Operating** -50 to 10,000 ft (-15.24 to 3,048 m)

Non-operating -50 to 40,000 ft (-15.24 to 12,192 m)

Industry Standard Certifications UL Yes
CSA Yes
FCC Compliance Yes

ENERGY STAR® Select models*

EPEAT Gold **

ICES Complete

Australia / Complete

NZ A-Tick Compliance

CCC Complete
Japan VCCI Compliance Complete
KC Complete
BSMI Complete
CE Marking Compliance Complete
MIL STD 810G Complete ***

For accessibility information on HP products, please visit: http://www.hp.com/accessibility.



^{*} Configurations of the HP ZBook 15 G5 that are ENERGY STAR® qualified are identified as HP ZBook 15 G5 ENERGY STAR® on HP websites and on http://www.energystar.gov.

^{**} EPEAT® registered where applicable. EPEAT registration varies by country. See http://www.epeat.net for registration status by country. See HP's 3rd party option store for solar energy accessory www.hp.com/go/options.

^{***} MIL STD 810G testing is pending and is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

Technical Specifications - Displays

DISPLAYS

15.6" diagonal FHD AG LED IPS (1920x1080) (220 nits) **Active Area** (W x H) 344.16 x 193.59mm **Dimensions** (W x H) 350.96 x 216.75mm

Weight 370 g

Diagonal Size15.6 in (39.6 cm)Surface TreatmentAnti-glareContrast Ratio600:1 (typical)

Refresh Rate 60 Hz

Brightness* 220 nits typical

Pixel Resolution Format 1920 x 1080 (FHD)

Configuration RGB Stripe

Interface eDP
Backlight LED
PPI 141

Viewing Angle 85/85/85 (Left/Right/Down/Up) (typical)

15.6" diagonal FHD AG LED IPS, with Ambient light sensor (1920x1080) (400 nits) **Active Area** (W x H) 344.16 x 193.59mm **Dimensions** (W x H) 350.96 x 216.75mm

Weight 370 g

Diagonal Size 15.6 in (39.6 cm)
Surface Treatment Anti-glare
Contrast Ratio 600:1 (typical)

Refresh Rate 60 Hz

Brightness* 400 nits (typical)

Pixel Resolution Format 1920 X 1800 (FHD)

Configuration RGB Stripe

InterfaceeDP + PSRBacklightLEDPPI141

Viewing Angle 85/85/85 (Left/Right/Down/Up) (typical)

HP Sure View Display 15.6" diagonal FHD AG LED IPS, Touch-Screen (1920x1080) (650 nits)

 Active Area (W x H)
 344.16 x 193.59mm

 Dimensions (W x H)
 350.96 x 216.75 mm

 Diagonal Size
 15.6 in (39.6 cm)

Weight 320 g
Surface Treatment Anti-glare
Contrast Ratio 600:1 (typical)

Refresh Rate 120 Hz

^{*} All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower."

^{*} All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower."

Technical Specifications - Displays

Brightness* 650 nits (typical)

Pixel Resolution Pitch 0.1793 x 0.1793 mm

Format 1920 X 1080 (FHD)

Configuration RGB Stripe

InterfaceeDP + PSRBacklightLEDPPI141

Viewing Angle 85/85/85 (Left/Right/Down/Up) (typical)

* All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower."

15.6" diagonal UHD AG LED IPS, Touch-Screen, with Ambient light sensor (3840x2160) (400 nits)

 Active Area (W x H)
 344.2176 x 193.6224mm

 Dimensions (W x H)
 350.96 x 216.95mm

 Diagonal Size
 15.6 in (39.6 cm)

Weight 320 g
Surface Treatment Anti-glare
Contrast Ratio 1200:1
Refresh Rate 60 Hz

Brightness* 400 nits (typical)

Pixel Resolution Format 3840 x 2160 (UHD)

Configuration RGB Stripe

InterfaceeDP + PSRBacklightLEDPPI282

Viewing Angle 85/85/85 (Left/Right/Down/Up) (typical)

* All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower."

HP Dream Color Display 15.6" diagonal UHD AG IPS 10 (8+2) bit color (3840x2160) (600 nits) 100% Adobe RGB

 Active Area (W x H)
 344.2176 x 193.6224 mm

 Dimensions (W x H)
 350.96 x 217.45 mm

 Diagonal Size
 15.6 in (39.6 cm)

Weight 380 g
Surface Treatment Anti-glare
Contrast Ratio 1200:1
Refresh Rate 60 Hz

Brightness* 600 nits (typical)

Pixel Resolution Format 3840 x 2160 (UHD)

Configuration RGB Stripe

Color Gamut Coverage 100 percent Adobe RGB

Interface eDP + PSR
Backlight LED
PPI 282

Viewing Angle 85/85/85 (Left/Right/Down/Up) (typical)

Technical Specifications - Displays

Integrate Color Calibration Sensor for HP DreamColor

Chipset AMS TCS3430

Sensor type XYZ tristimulus colorimeter

System interface I²C

Temperature range: -30 to 85° C

* All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower."

15.6" diagonal UHD AG LED IPS, with Ambient light sensor (3840x2160) (400 nits)

 Active Area (W x H)
 344.2176 x 193.6224mm

 Dimensions (W x H)
 350.96 x 216.95mm

 Diagonal Size
 15.6 in (39.6 cm)

Weight 320 g
Surface Treatment Anti-glare
Contrast Ratio 1200:1
Refresh Rate 60 Hz

Brightness* 400 nits (typical)

Pixel Resolution Format 3840 x 2160 (UHD)

Configuration RGB Stripe

InterfaceeDP + PSRBacklightLEDPPI282

Viewing Angle 85/85/85 (Left/Right/Down/Up) (typical)

* All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower."

Technical Specifications - Storage and Drives

STORAGE AND DRIVES

Internal Storage

Intel® Optane™ Memory (SSD 16 GB 2280 PCI3-3x2 NVMe 3D Xpoint) Form Factorial Capacity

Form Factor M.2 2280
Capacity 16 GB
NAND Type 3D Xpoint
Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Interface PCIe NVMe Gen3X2

Maximum Sequential

Read

900 MB/s

Maximum Sequential

Write

145 MB/s

Logical Blocks 28,181,188

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features L1.2

Must be configured with either a standard Hard Disk Drive or Solid-State Hybrid Drive. Cannot be configured with an additional M.2

2 TB 5400 rpm SATA Hard Drive Weight Disk Drive Capacity

Drive Weight 0.21 lbs (95 g)

Capacity 2 TB

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Transfer Rate Synchronous (maximum) 600 MB/s

Seek Time Single Track 1.5 ms
(typical reads, including settling) Average 13 ms

Maximum 32 ms

Cache128 MBRotational Speed5400 rpmLogical Blocks3,907,029,168

Operating Temperature 32° to 140° F (0° to 60° C) [case temp] **Features** ATA Security, S.M.A.R.T., NCQ, Ultra DMA

500 GB 7200 rpm SATA Hard Disk Drive Drive Weight0.21 lbs (95 g)Capacity500 GBHeight0.28 in (7 mm)

 Width
 2.75 in (69.85mm)

 Interface
 ATA-8, SATA 3.0

Transfer Rate Synchronous (maximum) 600 MB/s (Drive Capability)

Seek TimeSingle Track1.5 ms ~ 2 ms(typical reads, including settling)Average11 ms ~ 13 ms

Maximum 18 ms ~ 22 ms

Cache Up To 32 MB

Technical Specifications - Storage and Drives

Rotational Speed 7200 rpm **Logical Blocks** 976,773,168

Operating Temperature 32° to 140° F (0° to 60° C) [top cover temp] **Features** ATA Security, S.M.A.R.T., NCQ, Ultra DMA



Technical Specifications - Storage and Drives

1 TB 7200 rpm SATA Hard Drive Weight 0.21 lbs (95 g)

Disk Drive

Capacity 1 TB

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85mm)

 Interface
 ATA-8, SATA 3.0

Transfer Rate Synchronous (maximum) 600 MB/s (Drive Capability)

Seek TimeSingle Track1.5 ms(typical reads, including
settling)Average13 msMaximum32 ms

Cache128 MBRotational Speed7200 rpmLogical Blocks1,953,525,168

Operating Temperature 32° to 140° F (0° to 60° C) [top cover temp] **Features** ATA Security, S.M.A.R.T., NCQ, Ultra DMA

500 GB Hybrid Drive, 8 GB cache **Drive Weight** 0.20 lbs (92 g) ~ 0.21 lbs (95 g)

 Capacity
 500 GB

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Transfer Rate Synchronous (maximum) 600 MB/s

Seek Time Single Track 2 ms
(typical reads, including settling) Average 12 ms

Maximum 22 ms

CacheUp to 64MBRotational Speed5400 rpmLogical Blocks976,773,168

Operating Temperature 32° to 140° F (0° to 60° C) [case temp] **Features** ATA Security, S.M.A.R.T., NCQ, Ultra DMA

1 TB Hybrid Drive, 8 GB cache **Drive Weight** 90g **Capacity** 1 TB

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Transfer Rate Synchronous (maximum) 600 MB/s

Seek Time Single Track 1.5 ms 1.3 ms 1.3 ms 1.5 ms

Average 13 ms 1.5 ms 1.

CacheUp to 128MBRotational Speed5400 rpmLogical Blocks1,953,525,168

Operating Temperature 32° to 140° F (0° to 60° C) [case temp] **Features** ATA Security, S.M.A.R.T., NCQ, Ultra DMA

Technical Specifications - Storage and Drives

2 TB Hybrid Drive, 8 GB cache

Drive Weight 90g **Capacity** 2 TB

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Transfer Rate Synchronous (maximum) 600 MB/s
Seek Time Single Track 1.5 ms
(typical reads, including settling) Maximum 32 ms

CacheUp to 128MBRotational Speed5400 rpmLogical Blocks3,907,029,168

Operating Temperature 32° to 140° F (0° to 60° C) [case temp] **Features** ATA Security, S.M.A.R.T., NCQ, Ultra DMA

500 GB 7200 rpm SATA SED FIPS-140-2 compliant Hard Disk Drive

 Drive Weight
 0.21 lbs (95g)

 Capacity
 500 GB

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Transfer Rate Synchronous (maximum) 600 MB/s (Drive Capability)

Seek TimeSingle Track1.5 ms(typical reads, including
settling)Average12 msMaximum21 ms

 Cache
 32 GB

 Rotational Speed
 7200 rpm

 Logical Blocks
 976,773,168

Operating Temperature 32° to 140° F (0° to 60° C) [top cover temp]

Features ATA Security; TCG Opal 2.x, FIPS, S.M.A.R.T., NCQ, Ultra DMA

* FIPS-certified, hardware-based AES-256 encryption image.

500 GB 7200 rpm SATA SED Hard Disk Drive

 Drive Weight
 0.21 lbs (95g)

 Capacity
 500 GB

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Transfer Rate Synchronous (maximum) 600 MB/s (Drive Capability)

Seek TimeSingle Track1.5 ms(typical reads, including settling)Average12 msMaximum21 ms

Cache 32 MB
Rotational Speed 7200 rpm
Logical Blocks 976,773,168



Technical Specifications - Storage and Drives

32° to 140° F (0° to 60° C) [case temp] **Operating Temperature**

ATA Security, TCG Opal 2.x, S.M.A.R.T., NCQ, Ultra DMA **Features**

256 GB SATA TLC Solid State Drive (2.5")

Drive Weight 0.17 lb (78 g) 256 GB Capacity Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface **ATA-8, SATA 3.0**

NAND TLC Form Factor (I/O) 2.5 inch

Performance Maximum Sequential Read Maximum Sequential Write

> 530 MB/s~560 MB/s 500 MB/s~525 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

ATA Security; DIPM; TRIM; DEVSLP **Features**

1 TB SATA TLC Solid State Drive Weight Drive (2.5")

0.17 lb (78 g)

Capacity 1 TB Height 0.28 in (7 mm) Width 2.75 in (69.85 mm)

Interface **ATA-8, SATA 3.0**

NAND TLC Form Factor (I/O) 2.5 inch

Performance Maximum Sequential Read Maximum Sequential Write

> 500 MB/s ~ 530 MB/s 530 MB/s ~ 560 MB/s

Logical Blocks 2,000,409,264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; DIPM; TRIM; DEVSLP

256 GB M.2 SED TLC Solid

State Drive

Drive Weight 0.02 lb (<10 g) Capacity 256 GB

Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Interface **ATA-8, SATA 3.0**

NAND TLC Form Factor (I/O) M.2 2280

Performance Maximum Sequential Read Maximum Sequential Write

> 530 MB/s ~ 560 MB/s 500 MB/s ~ 530 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security; TCG Opal 2.0, DIPM; TRIM; DEVSLP

Technical Specifications - Storage and Drives

512 GB M.2 FIPS-140-2 TLC Solid State Drive
 Drive Weight
 0.02 lb (<10 g)</td>

 Capacity
 512 GB

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Generation
 Micron 1100

NAND Type TLC
Form-Factor (I/O) M.2 2280
Interface ACS-3, SATA 3.2

NAND TLC Form Factor (I/O) M.2 2280

Performance Maximum Sequential Read Maximum Sequential Write

Up to 530MB/s Up to 400MB/s

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0; FIPS; DIPM; TRIM; DEVSLP

360 GB TLC Solid State Drive

 Drive Weight
 0.02 lb. (10 g)

 Capacity
 360 GB

Height0.09 in (2.3 mm)Width0.87 in (22 mm)GenerationIntel® Pleasant Star

NAND Type TLC Form-Factor (I/O) M.2 2280

Interface PCIe NVMe Gen3X4

Performance Maximum Sequential Read Maximum Sequential Write

Up to 1700MB/s(Compressible

Performance)

Up to 1260 MB/s

Logical Blocks 703,282,608

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option); TRIM; L1.2

256 GB M.2 NVMe TLC Solid State Drive **Drive Weight** 0.02 lb (<10 g) **Capacity** 256 GB

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

Generation Samsung PM961/ Toshiba XG5

NAND Type TLC Form-Factor (I/O) M.2 2280

Interface PCIe NVMe Gen3X4

Performance Maximum Sequential Read Maximum Sequential Write

2580 MB/s ~ 2600 MB/s 1000 MB/s ~ 1100 MB/s

Logical Blocks 500,118,192

Technical Specifications - Storage and Drives

32° to 158°F (0° to 70°C) [ambient temp] Operating Temperature

Features ATA Security (Option), TRIM; L1.2

256 GB

256 GB M.2 NVMe TLC SED Drive Weight 0.02 lb (<10 q) **Solid State Drive**

Capacity

0.09 in (2.3 mm) Height Width 0.87 in (22 mm)

Generation Samsung PM961 SED Opal2/ Toshiba XG5 SED Opal2

NAND Type TLC Form-Factor (I/O) M.2 2280

PCIe NVMe Gen3X4 Interface

Performance Maximum Sequential Read Maximum Sequential Write

> 2580 MB/s ~ 2600 MB/s Up to 1000 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

ATA Security (Option); TCG Opal 2.0; TRIM; L1.2 **Features**

512 GB M.2 NVMe TLC **Solid State Drive**

Drive Weight 0.02 lb (<10 g)

Capacity 512 GB

Height 0.09 in (2.3 mm) Width 0.87 in (22 mm)

Generation Samsung PM981 / Toshiba XG5

NAND Type TLC Form-Factor (I/O) M.2 2280

Interface PCIe NVMe Gen3X4

Performance Maximum Sequential Read Maximum Sequential Write

> 1000 MB/s ~ 1800 MB/s 2800 MB/s ~ 2900 MB/s

Logical Blocks 1,000,215,215

32° to 158°F (0° to 70°C) [ambient temp] Operating Temperature

Features ATA Security, TRIM; L1.2

512 GB M.2 NVMe TLC SED Drive Weight 0.02 lb (<10 g) **Solid State Drive**

Capacity 512 GB

Height 0.09 in (2.3 mm) Width 0.87 in (22 mm)

Generation Samsung PM981 SED Opal2/ Toshiba XG5 SED Opal2

NAND Type TLC Form-Factor (I/O) M.2 2280

Interface PCIe NVMe Gen3X4

Performance Maximum Sequential Read Maximum Sequential Write

> 2800 MB/s ~ 2900 MB/s 1000 MB/s ~ 1800 MB/s

Logical Blocks 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]



Technical Specifications - Storage and Drives

Features ATA Security (Option); TCG Opal 2.0; TRIM; L1.2

1 TB, M.2 NVMe TLC Solid Drive Weight

State Drive

Drive Weight 0.02 lb (<10 g)

Capacity 1 TB

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

Generation Samsung PM981 / Toshiba XG5

NAND Type TLC Form-Factor (I/O) M.2 2280

Interface PCIe NVMe Gen3X4

Performance Maximum Sequential Read Maximum Sequential Write

2900 MB/s ~ 3000 MB/s Up to 2000MB/s

Logical Blocks 2,000,409,264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security, TRIM; L1.2

2 TB, M.2 NVMe TLC Solid Drive Weight

State Drive

Orive Weight 0.02 lb (<10 g)

Capacity 2 TB

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Generation
 Toshiba XG5P

NAND Type TLC
Form-Factor (I/O) M.2 2280

Interface PCIe NVMe Gen3X4

Performance Maximum Sequential Read Maximum Sequential Write

Logical Blocks 3,907,029,168

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security, TRIM; L1.2



^{*}For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) disk is reserved for system recovery software.

Technical Specifications - Security

SECURITY

HP Fingerprint Reader

Mobile Voltage Operation 3.0V-3.6V Single Supply **Operating Temperature** 14° - 167°F (-10° - 75°C)

Current consumption image 36mA

Low latency wait for finger 950 uA

Capture rate 3000 lines/sec

ESD Resistance IEC 6100-4-2 4B (+/-15KV)

Detection Matrix 200*1 (plus another secondary line); 508 dpi, sensor area 12*3 mm

S	ma	rt	Ca	rd
D	دم	db	r	

Smart card standard

PC/SC 2.0 for Windows smart card standard

Dimensions (L x W x H) 0.41x 0.08 x 0.32 in (10.5 x 2 x 8.2 mm)

Smart Card support

ISO 7816 Class A and AB smart cards

Smart Card Interface Smart Card Interface with T = 0 and T = 1 support Support I2C memory card, SLE4418, SLE4428,

SLE4432, SLE4442, SLE4436,

SLE5536, SLE6636, AT88SC1608, AT45D041 card and AT45DB041 card via

external EEPROM

Operating systems

Normal Mode With card present, before being suspended: 40.9 mA Without card present, before being suspended: 33.16 mA After being suspended with smart card present: 380 µA

After being suspended without smart card present: 380 µA

Features

Power Saving Mode: With card present, before being suspended: 40.6 mA Without card present: 380 µA After being suspended with smart card present: 380 µA

- Support single slot
- Support TO, T1 protocol
- Support I2C memory card, SLE4418, SLE4428, SLE4432, SLE4442, SLE4436,
- SLE5536, SLE6636, AT88SC1608, AT45D041 card and AT45DB041 card via external EEPROM
- Support ISO7816 Class A, B and C (5V/3V/1.8V) card
- Implemented as an USB full speed device with bulk transfer endpoint, Mass
- Storage endpoint
- Built-in PLL for USB and Smart Card clocks requirement
- Support EEPROM for USB descriptors customization (PID/VID/ iManufacturer/iProduct/Serial Number), Direct Web Page Link, and accessing memory card module.
- EEPROM programmable via USB interface
- Support software update for memory card module
- Support Direct Web Page Link via configuration in external EEPROM Support short APDU and extended APDU
- Compatible with Microsoft USB-CCID driver
- Support remote wake up through inserting card/removing card
- Support USB selective suspend



Technical Specifications - Security

- Support Power Saving Mode (Using one pin to select between Normal/PWR Saving Mode)
- Support card power over current protection mechanism
- Built in resonator.
- Support USB LPM (Link Power Management) features.
- Embedded clock source.



Technical Specifications – Networking

NETWORKING/COMMUNICATION

Intel® I219-LM Gigabit Network Connection Ethernet Features 10 Mbit/s operation (10BASE-T; IEEE 802.3; IEEE 802.3 clauses 13-

14)

100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses

21-30)

1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023.

Clauses 40)

IEEE 802.3u Auto-Negotiation (Automatic Speed Selection)

Full Duplex Operation at all Speeds, Half Duplex operation at 10 and

100 Mbit/s

IEEE 802.1p QoS (Quality of Service) Support

IEEE 802.1q VLAN support

IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)

IEEE 802.3az EEE(Energy Efficient Ethernet)

IEEE 802.1as/1588 conformance

Jumbo Frame 9K

Auto MDI/MDIX Crossover cable detection

Power ACPI compliant - multiple power modes

Management Energy Potest Low Power Meda (Green Ether

ManagementEnergy Detect Low Power Mode(Green Ethernet)PerformanceTCP/IP/UDP Checksum Offload (configurable)

Features Protocol Offload(ARP & NS)

Large send offload and Giant send offload

Receiving Side Scaling MACSec Offload (802.3ae)

Intel® vPro™ iSCSI Boot

RSS (Receive Side Scaling)

Ultra Low Power

Manageability Wake-on-LAN from standby and hibernation (Magic Packet and

Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet

only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB

(802.3x, clause 30))

Comprehensive diagnostic and configuration software suite

Virtual Cable Doctor for Ethernet cable status

Interface PCI Express 1.1 x1 to fully support ASPM LOs/L1 and CLKREQ.

NOTE: Intel[®] I219-LM Gigabit interface is not PCIe compliant. It operates at half of PCIe specification V1.1 (2.5GT/S) speed.

NIC Device Driver Name Intel® Ethernet Network Connection I219-LM



Technical Specifications – Networking

Intel® XMMTM 7360 LTE-**Advanced**

Technology/Operating bands

FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 2100 (Band 66). TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41). HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz

3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW Wireless protocol standards

> throughput up to 450Mbps; UL 20MHz throughput up to 50Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B and XTRA)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou

1561.098 MHz

Maximum data rates LTE: 450 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps

(Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76

Mbps (Upload)

Maximum output power LTE: 23 dBm HSPA+: 23.5 dBm

LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); Maximum power consumption

800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight

Dimensions 1.65 x 1.18 x 0.09 in (42 x 30 x 2.3 mm)

(Length x Width x Thickness)

HP lt4132 LTE/HSPA+ 4G **Mobile Broadband Module** Technology/Operating bands LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3) MHz,

850 (Band 5), 2600 (Band 7), 900 (Band 8) MHz,

800 (Band 20), 700 (Band 28) MHz.

HSPA+: 2100 (Band 1), 1900 (Band 2), 850 (Band 5), 900 (Band 8)

E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8)

Wireless protocol standards 3GPP Release 10 LTE Specification CAT.4, 20MHz BW

> WCDMA R99. 3GPP Release 5. 6. 7 and 8 UMTS Specification E-GPRS: Class B, Multi-slot class 12, coding schemes CS1 - CS4

and MSC1 - MSC9

GPS Standalone, A-GPS (MS-B and LTO)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz

Maximum data rates LTE: 150 Mbps (Download), 50 Mbps (Upload)

> DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)

Maximum output power LTE: 23 dBm



^{*} Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Technical Specifications – Networking

HSPA+: 23.5 dBm

E-GPRS 1900/1800: 26 dBm E-GPRS 900/850: 27 dBm GPRS 1900/1800: 29.5 dBm GPRS 900/850: 32.5 dBm

Maximum power consumption LTE: 1,200 mA (peak); 900 mA (average)

HSPA+: 1,100 mA (peak); 800 mA (average) E-GPRS: 2,600 mA (peak); 500 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6 g

Dimensions 42 x 30 x 2.3 mm

(Length x Width x Thickness)



^{*} Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Technical Specifications - Networking

Intel® Dual Band Wireless-AC Wireless LAN Standards

9560AC 802.11 a/b/g/n/ac

(2x2) WiFi + Bluetooth 5.0

Combo Adaptor

IEEE 802.11b

IEEE 802.11g

IEEE 802.11n

IEEE 802.11n

Interoperability Wi-Fi certified

Frequency Band 802.11b/g/n 2.402 - 2.482 GHz

Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise

disable those channels

802.11a/n 4.9 - 4.95 GHz (Japan)

5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz

Note: Indonesia only supports 5.725 - 5.825 GHz

(CH149 - CH161)

Data Rates 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15 (20MHz and 40MHz)

802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and

80MHz)

Modulation Direct Sequence Spread Spectrum

CCK, BPSK, QPSK, 16-QAM, 64-QAM, 256-QAM

• IEEE and WiFi compliant 64 / 128 bit WEP encryption for

a/b/g mode only

AES-CCMP: 128 bit in hardware

802.1x authentication

WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification

IEEE 802.11i

Cisco Certified Extensions, all versions through CCX4 and

CCX Lite

WAPI

Network Architecture Ad-hoc (Peer to Peer)

Models Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between band Access Points

Output Power² 802.11b: +16dBm minimum

802.11g: +14dBm minimum 802.11a: +14dBm minimum

802.11n HT20(2.4GHz): +14dBm minimum 802.11n HT40(2.4GHz): +12dBm minimum 802.11n HT20(5GHz): +14dBm minimum 802.11n HT40(5GHz): +12dBm minimum

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ 802.11b, 1Mbps: -94dBm maximum



Technical Specifications – Networking

802.11b, 11Mbps: -86dBm maximum 802.11g, 6Mbps: -88dBm maximum 802.11g, 54Mbps: -74dBm maximum 802.11a, 6Mbps: -88dBm maximum 802.11a, 54Mbps: -74dBm maximum 802.11n, MCS07: -69dBm maximum 802.11n, MCS15: -66dBm maximum 802.11ac, 1SS, MCS-0: -86dBm maximum 802.11ac, 2SS, MCS-9: -61dBm maximum 802.11ac, 2SS, MCS-9: -58dBm maximum

Antenna Type High efficiency antenna with spatial diversity, mounted in the

display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth

communications

Form Factor PCI-Express M.2 MiniCard

Dimensions Type 2230 : 2.3 x 22.0 x 30.0 mm

0r

Type 1630: 2.3 x 16.0 x 30.0 mm

Weight Type 2230 : 2.8g

0r

Type 1630 : 2g 3.3v +/- 9%

Operating Voltage 3.3v +/- 9%
Temperature Operating

Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber - Radio OFF; LED White - Radio ON

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
- * Wireless access point and internet service required. Availability of public wireless access points limited.

HP Integrated Module with Bluetooth 4.2 Wireless Technology

Bluetooth Specification 4.2 Compliant **Frequency Band** 2402 to 2480 MHz

Number of AvailableLegacy : 0~79 (1 MHz/CH)ChannelsBLE : 0~39 (2 MHz/CH)

Data Rates and Throughput Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps,

voice channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth

device with a maximum transmit power of + 4 dBm for BR and EDR.



Technical Specifications - Networking

Receiver Sensitivity

Modulation	0.01% BER	0.001% BER		
GFSK	-80 dBm	-70 dBm		
π/4-DQPSK	-80 dBm	-70 dBm		
8DPSK	-80 dBm	-70 dBm		

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Range Legacy Up to 33 ft (10 m)

BLE Up to 99 ft (30 m)

USB 2.0 compliant

Electrical Interface

Bluetooth Software

Supported

Microsoft Windows® Bluetooth Software

Link TopologyPoint to Point, Multipoint Pico Nets up to 7 slavesSecurityFull support of Bluetooth Security ProvisionsPower ManagementMicrosoft Windows® ACPI, and USB Bus Support

Self-configurable to optimize power conservation in all operating

modes, including Standby, Hold, Park, and Sniff

Certifications All necessary regulatory approvals for supported countries,

including:

FCC (47 CFR) Part 15C, Section 15.247 & 15.249

ETS 300 328, ETS 300 826 Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles Supported

Serial Port Profile (SPP)

Service Discovery Application Profile (SDAP)

Dial-Up Networking (DUN)

Generic Object Exchange Profile (GOEP)

Object Push Profile (OPP)

Hard Copy Cable Replacement (HCRP) Personal Area Networking Profile (PAN) Human Interface Device Profile (HID)

Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)
Audio Video Remote Control Profile (AVRCP)

Near Field Communications (NFC) Controller (optional)

Controller Supports

NFC Mirage WNC XRAV-1 (NXP NPC300 I2C 10mmx17mm)

Windows 8, Proximity Events

Windows 7, PC/SCNFC Forum Compliant

• Near Field Communications Controller

Dimensions (L x W x H) Module 25 mm by 10 mm by 2.0 mm

Chipset NPC100 System interface I2C

NFC RF standards standards ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC

18092 ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2

NFC Forum Support Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2

Technical Specifications – Networking

Reader (PCD-VCD) Mode(1) ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693

MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards

Card Emulation (PICCVICC)

Mode ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa

Frequency 13.56 MHz

NFC Modes Supported Reader/Writer, Peer-to-Peer **Raw RF Data Rates** 106, 212, 424, 848 kbps

Operating temperature 0°C to 70°C **Storage temperature** -20°C to 125°C

Humidity 10-90% operating 5-95% non-operating

Supply Operating voltage 2.97 to 5.5 Volts **I/O Voltage** 1.8V or 3.3V

Power Consumption Booster enable, VBAT= 3.3V,

VCC_BOOST = 5V) Typical² Polling 7.3 mA Detected Test Tag Type Mode Power 1 Total 283.8 mA Net Module 236.8 mA Consumption, Detected Test Tag Type 2 Total 288.8 mA Net

Module 241.8 mA Detected Test Tag Type 3
Total 287.7 mA Net Module 240.7 mA Detected
Test Tag Type 4 Total 282.3 mA Net Module

235.3 mA

Antenna connector 0.5mm pitch, 7 connector FPC. Antenna matching is external to

module.

Notes 1. With application or UICC support

2. Actual Power Consumption is dependent on NFC antenna and matching circuit and on the particular polling sequence

and period configured.

Technical Specifications - Audio and Multimedia

AUDIO/MULTIMEDIA – BANG & OLUFSEN

Hardware Implementation Synaptics CX8400 with two NXP TFA9891 discrete smart amplifiers

Function Key Volume up, volume down, and mute

Volume Controls

Full Duplex Yes
Microphone In Stereo
Headphone/Line Out Stereo

Integrated Microphone Yes, three digital microphone array when equipped with optional webcam

Audio Output Quality Frequency Response 20 Hz - 20 kHz

Signal to Noise Ratio 106dB (DAC), 102dB (ADC)

Total Harmonic 91dB THD+n on LineOut/HP (0.003%)

Distortion

Noise Floor -110 dB
Play Sampling Rate(s) Up to 192kHz
Record Sampling Rate(s) Up to 96kHz
DAC 16, 20 or 24-bit
ADC 16, 20 or 24-bit

Internal Stereo Speaker Power Rating 1 Watt/per speaker

Impedance 8 ohms/per speaker



Technical Specifications - Power

POWER

HP 150W Slim Smart AC Adapter

Dimensions 6.02 x 2.60 x .87 in (153 x 66 x 22 mm)

Weight 0.70 lbs (320 q) Input 100 to 240 VAC

> 88% min at 115 VAC Input Efficiency

Input frequency range 47 to 63 Hz

2.9 A at 90 VAC, 1.45 A at 180 VAC Input AC current

Output Output power 150W DC output 19.5V

Hold-up time

5 msec at 115 VAC input

Output current limit <16A, Over voltage protection- 29V max

automatic shutdown

Connector 3 pin/grounded, mates with interchangeable cords **Environmental Design** Operating 32° to 104° F (0° to 40° C)

temperature

Non-operating (storage) -4° to 149° F (-20° to 65° C)

temperature

Altitude 0 to 10,000 ft (0 to 3,048 m)

Humidity 20% to 80% Storage Humidity 10% to 90%

EMI and Safety Certifications

CE Mark- full compliance with LVD and EMC directives; Worldwide safety standards- IEC950, EN60950, UL1950, Class 1, SELV; Agency approvals- C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCIB, NOM-1 NYCE; MTBF- over 200,000 hours at 25°C ambient condition.

HP Long Life 4-cell Polymer Battery (90 WHr)

Dimensions $(H \times W \times L)$ 10.15x2.49x0.521 in(25.8x6.32x1.324 cm)

Weight (max) 0.82lb (372q) Cells/Type 4-cell; Polymer

Energy Voltage 15.4V

> Amp-hour capacity 5.84Ah Watt-hour capacity 90Wh

Temperature Operating (Charging) 32° to 113° F (0° to 45° C)

> Operating (Discharging) 14° to 140° F (-10° to 60° C)

> Non-operating -4° to 140° F (-20° to 60° C)

Battery Re-Charge Time System in OFF or Standby 3 hours

Mode

System ON 3 to 5 hours

Charge Rate 0.7C; HP Fast Charge 90% in 90 minutes

Fuel Gauge LED No Warrantv* 3 year Compatible with optional N/A

Travel Battery

* 3-year platform warranty is required for a 3-year Long Life Battery warranty.

Technical Specifications - Environmental Data

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®

11EVAC COU-

- US Federal Energy Management Program (FEMP)
- EPEAT® GOLD registered in the United States. See http://www.epeat.net for registration status in your country.

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".

SOUNC FOU-

100VAC FOU-

Energy Consumption (in accordance with US ENERGY STAR® test method)

STAR" (est illetilou)	I I SVAC, OUNZ	ZSUVAC, SUNZ	IUUVAC, SUNZ
Normal Operation (Sort idle)	11.20 W	10.51 W	11.24 W
Normal Operation (Long idle)	6.70 W	6.30 W	6.37 W
Sleep	1.13 W	1.12 W	1.14 W
Off	0.41 W	0.43 W	0.42 W

Note:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*			
Normal Operation (Short idle)			
Normal Operation (Long idle)			
Sleep			
Off			

115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
38 BTU/hr	36 BTU/hr	38 BTU/hr
23 BTU/hr	22 BTU/hr	22 BTU/hr
4 BTU/hr	4 BTU/hr	4 BTU/hr
1.4 BTU/hr	1 BTU/hr	1 BTU/hr

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)

Typically Configured – Idle Fixed Disk – Random writes

Longevity and Upgrading

Sound Power (LwAd, bels)	Sound Pressure (L _{pAm} , decibels)
3.2	22
3.2	21

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

- 3 USB ports
- 2 Thunderbolt™ 3 ports
- 1 2.5" Storage Bay Drive
- 2 M.2 SATA SED Solid State Drives
- 1 Smart Card reader



Technical Specifications - Environmental Data

- 4 SODIMM memory slots
- 1 HDMI 1.4 port

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight

Battery size: CR2032 (coin cell)

Battery type: Lithium

Battery size: 6-cell high capacity Lithium-Ion battery (optional 8 cell available)

Battery type:

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product contains 0.0% post-consumer recycled plastic (by wt.)
- This product is 95.6% recycle-able when properly disposed of at end of life.

ш	-	•	•	3	a	111	•	M	-	+0	-	ıc
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External:	PAPER/Corrugated	383 g
Internal:	PLASTIC/Polyethylene Expanded - EPE	90 g
	PLASTIC/Polyethylene low density - LDPE	10 g
	PLASTIC/Polypropylene - PP	5 g

The plastic packaging material contains at least 81.5% recycled content.

The corrugated paper packaging materials contains at least 80 % recycled content.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/qse.pdf):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries



Technical Specifications - Environmental Data

- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP Inc.offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the HP Inc. web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf



Technical Specifications - Environmental Data

COUNTRY OF ORIGIN

China



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part #
Display	HP DreamColor Z31x Studio Display	Z4Y82A8
Memory	HP 4GB DDR4-2666 SODIMM	TBD
-	HP 8GB DDR4-2666 SODIMM	TBD
	HP 16GB DDR4-2666 SODIMM	TBD
	HP 8GB DDR4-2666 ECC SODIMM	TBD
	HP 16GB DDR4-2666 ECC SODIMM	TBD
Cases	HP Slim Ultrabook Messenger (up to 15.6" x .88"/22/5mm)	F3W14AA
	HP Slim Ultrabook Backpack (up to 15.6" x .88"/22/5mm)	F3W16AA
	HP Essential Backpack (up to 15.6")	H1D24AA
	HP Essential Top Load Case (up to 15.6")	H2W17AA#xxx
Docking	HP USB-C Universal Dock	1MK33AA
-	HP USB-C Mini Dock	1PM64AA
	HP Thunderbolt™ Dock 230W G2	2UK38AA
	HP Thunderbolt Dock Audio	3AQ21AA
	HP USB-C Dock G4	3FF69AA#xxx
	HP TB Dock G2 w/Combo Cable	3TR87AA#xxx
	HP Travel Hub	TOK30AA
	HP 3005pr USB 3.0 Port Replicator w/ USB-C™ Adapter	Y4H06AA
Input/Output -	HP Wireless Premium Mouse	1JR31AA
Mice	HP USB Premium Mouse	1JR32AA
	HP Slim Bluetooth Mouse	F3J92AA#xxx
	HP USB Travel Mouse	G1K28AA#xxx
	HP Comfort Grip Mouse	H2L63AA
	HP X4000 Bluetooth Mouse	H3T50AA#xxx
	HP 3-Button Laser Mouse	H4B81AA#xxx
	HP Ultra Mobile Wireless Mouse	H6F25AA#xxx
	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP Slim USB Keyboard and Mouse	T6T83AA
	HP Wireless (Link-5) Keyboard	T6U20AA
Power Adapters	HP 150W Slim Smart AC Adapter	4SC18UT#xxx
	HP 200W Slim Smart AC Adapter	4SC19UT#xxx
Battery	ZBook G5 Replacement Battery 90Whr Battery	Battery
Adapters	HP HDMI to DVI adapter	F5A28AA
	HDMI to VGA Adapter	H4F02AA
	USB 3.0 to RJ45	N7P47AA
	HP USB-C™ to VGA Adapter	N9K76AA
15		



Options and Accessories (sold separately and availability may vary by country)

USB-C to RJ45 V7W66AA HP USB-C™ to USB Hub Z6A00AA Collaboration **HP Elite Presenter Mouse** 2CE30AA#xxx K8P74AA#xxx **HP UC Conferencing Keyboard** HP Stereo 3.5mm Headset T1A66AA **HP Stereo USB Headset T1A67AA HP USB Collaboration Keyboard Z9N38AA HP Wireless Collaboration Keyboard** Z9N39AA#xxx **HP Wireless Premium Keyboard** Z9N41AA#xxx Storage - External HP 256GB M2 NVME PCIe SSD (2280) V3K66AA Storage HP 512GB M2 NVME PCIe SSD (2280) V3K67AA HP 256GB TLC PCI-e 3x4 NVMe M.2 SSD 1FU87AA HP 512GB TLC PCI-e 3x4 NVMe M.2 SSD 1FU88AA **HP External USB DVDRW Drive** F2B56AA Security **HP Nano Keyed Cable Lock** 1AJ39AA HP Nano Dual Head Keyed Cable Lock **1AJ41AA HP Docking Station Cable Lock** AU656AA#XXX HP 15.6" Notebook PC Privacy Filter J7H71AA **HP Keyed Cable Lock** TOY14AA **HP Combination Lock** TOY15AA **HP Essential Combination Lock** TOY16AA HP Keved Cable Lock 10mm **T1A62AA** HP Dual Head Cable Lock (Non-Master key) **T1A64AA** HP Dual Head Cable Lock (Master Key) **T1A65AA** HP 3 year Next business day onsite Hardware Support w/Accidental Damage **UF631E** Protection-G2 for Notebooks



Summary of Changes

Date of change:	Version History:		Description of change:
June 7. 2018	From v1 to v2	Changed	Format changes
June 26, 2018	From v2 to v3	Changed	Front view, Processors, Storage and Drives, Software and Security, Power, System Unit, Security sections and format changes



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